

Dual N-Channel 30-V Power MOSFET

GENERAL DESCRIPTION

The LT4920C is the N-Channel logic enhancement mode power field effect transistors, using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on state resistance.

These devices are particularly suited for low voltage application such as cellular phone, notebook computer power management and other battery powered circuits, and low in-line power loss that are needed in a very small outline surface mount package.

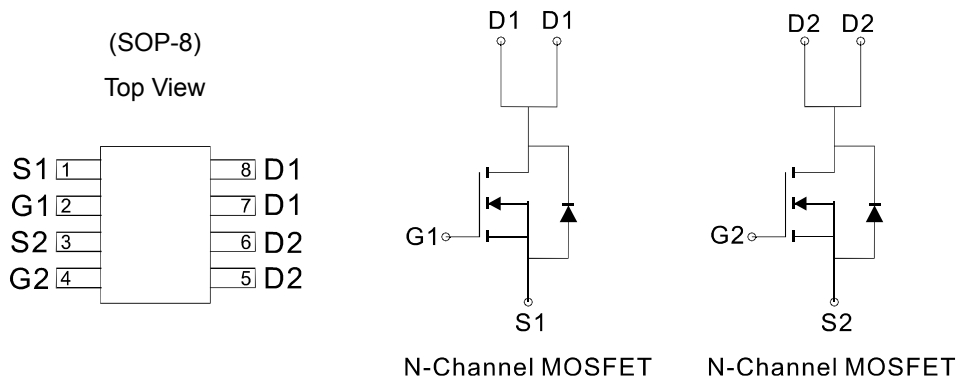
FEATURES

- 30V/6.9A, $R_{DS(ON)}=35\text{ m}\Omega$ @ $V_{GS}=10\text{V}$
- 30V/5.8A, $R_{DS(ON)}=45\text{ m}\Omega$ @ $V_{GS}=4.5\text{V}$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

PIN CONFIGURATION



Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ($t_J=150^\circ\text{C}$)	I_D	$T_A=25^\circ\text{C}$	6.9
		$T_A=70^\circ\text{C}$	5.5
Pulsed Drain Current	I_{DM}	30	A
Continuous Source Current (Diode Conduction)	I_S	1.7	A
Maximum Power Dissipation	P_D	$T_A=25^\circ\text{C}$	2
		$T_A=70^\circ\text{C}$	1.3
Operating Junction Temperature	T_J	-55 to 150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient*	$R_{\theta JA}$	$T \leq 10\text{ sec}$	50
		Steady State	80
Thermal Resistance-Junction to Case	$R_{\theta JC}$	50	$^\circ\text{C}/\text{W}$

The device mounted on 1in² FR4 board with 2 oz copper

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Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless Otherwise Specified)

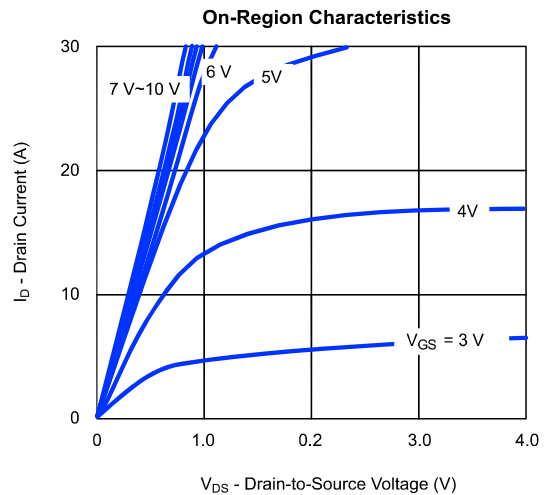
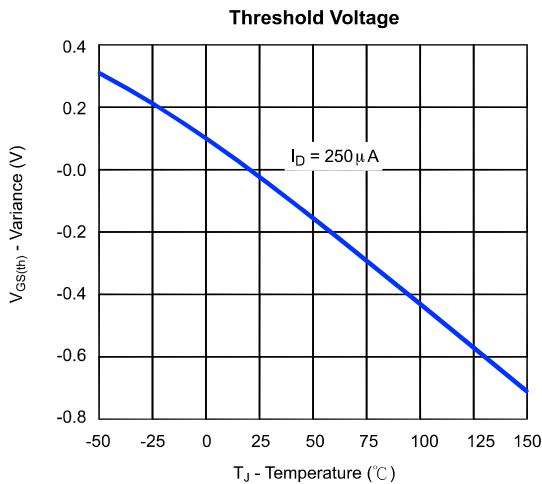
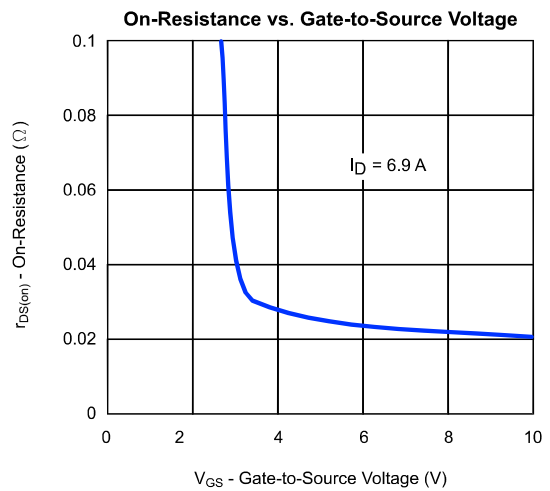
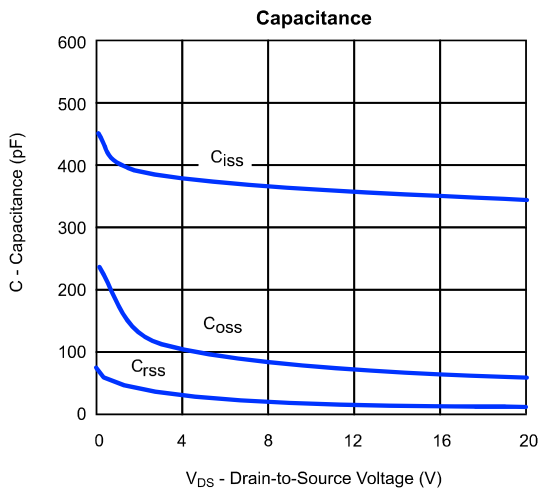
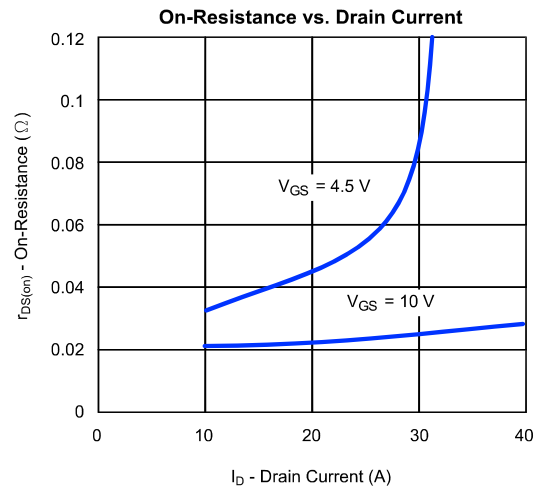
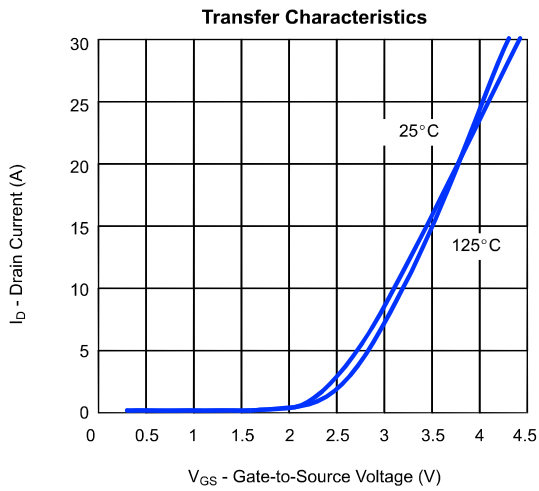
Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\ \mu\text{A}$	1	1.4	3	V
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$			1	μA
		$V_{DS}=30\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			25	
$I_{D(ON)}$	On-State Drain Current ^a	$V_{DS}\geq 5\text{V}, V_{GS}=10\text{V}$	20			A
$R_{DS(ON)}$	Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=6.9\text{A}$		26	35	m Ω
		$V_{GS}=4.5\text{V}, I_D=5.8\text{A}$		36	45	
G_{FS}	Forward Transconductance	$V_{DS}=15\text{V}, I_D=6.9\text{A}$		25		S
V_{SD}	Diode Forward Voltage	$I_S=1.7\text{A}, V_{GS}=0\text{V}$		0.75	1.2	V
DYNAMIC^b						
Q_g	Total Gate Charge	$V_{DS}=15\text{V}, V_{GS}=10\text{V}, I_D=6.9\text{A}$		11.5	15	nC
Q_{gs}	Gate-Source Charge			2.7		
Q_{gd}	Gate-Drain Charge			2.3		
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V},$ $f=1\text{MHz}$		350	450	pF
C_{oss}	Output Capacitance			65		
C_{rss}	Reverse Transfer Capacitance			16		
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=15\text{V}, R_L=15\ \Omega$ $I_D=1\text{A}, V_{GEN}=10\text{V}$ $R_G=6\ \Omega$		9	12	ns
t_r	Turn-On Rise Time			10	23	
$t_{d(off)}$	Turn-Off Delay Time			32	40	
t_f	Turn-Off Fall Time			3.5	5	
t_{rr}	Surce-Drain Reverse Recovery Time	$I_F=1.7\text{A}, di/dt=100\text{A}/\mu\text{s}$		50	90	ns

Notes

a. pulse test:pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$, Guaranteed by design, not subject to production testing.

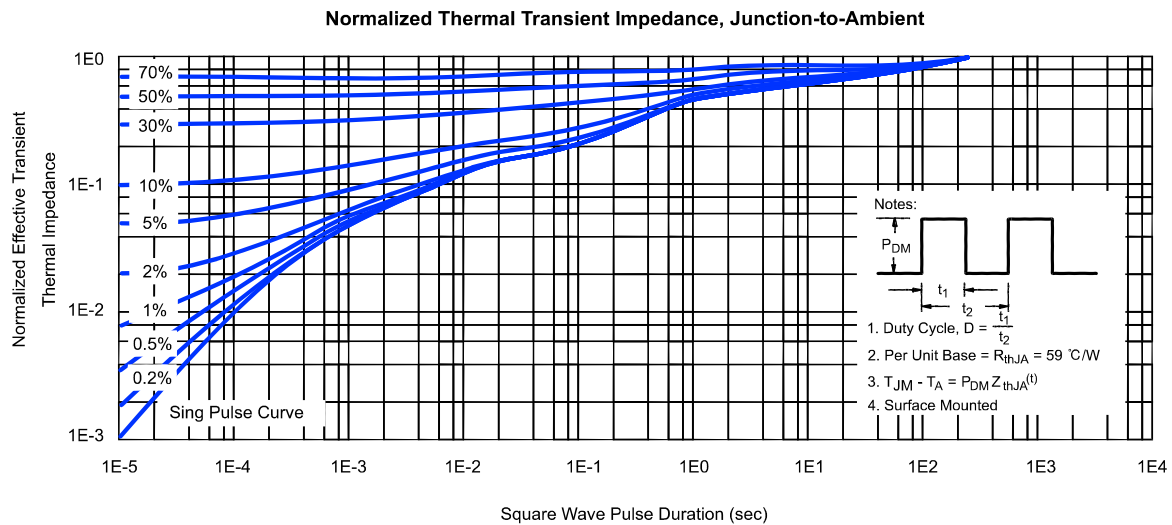
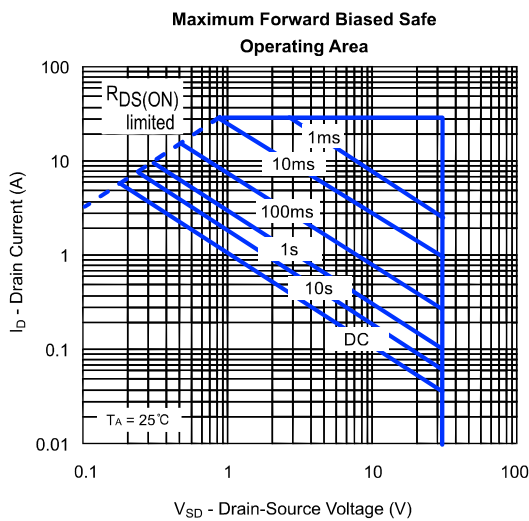
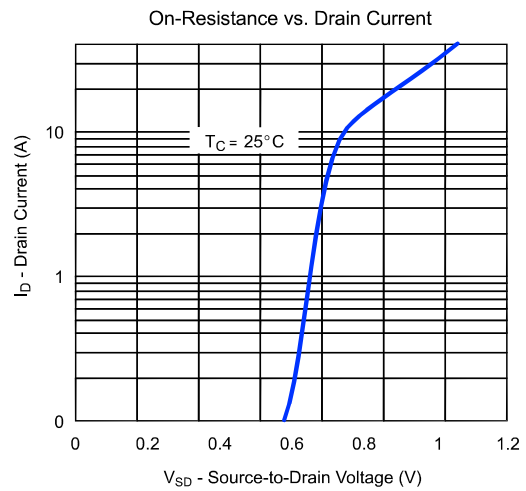
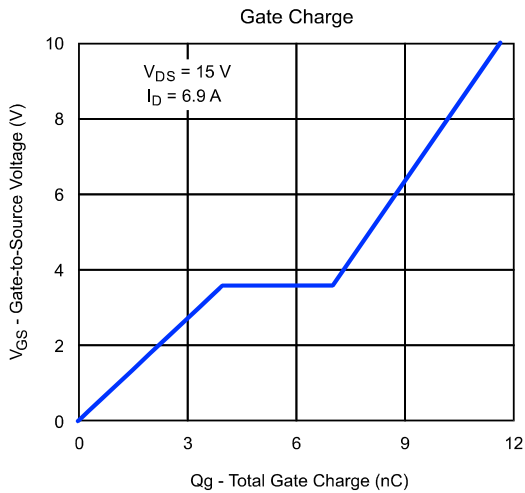
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Typical Characteristics (T_J = 25°C Noted)



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SOP-8 Package Outline

